

Thermal Characteristics

| Characteristic | | Symbol | Value | Unit |
|---|---------------------------------|-----------------------------------|-------------|------|
| Peak Pulse Power (tp = 8 x 20µs) | (Note 5) $T_A = +25^{\circ}C$ | P _{pk} | 25 | W |
| Power dissipation | (Note 5) $T_A = +25^{\circ}C$ | P_{D} | 385 | mW |
| Thermal Resistance, Junction to Ambient | (Note 5) T _A = +25°C | $R_{\Theta JA}$ | 325 | °C/W |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -55 to +150 | °C |

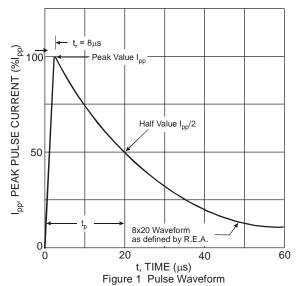
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

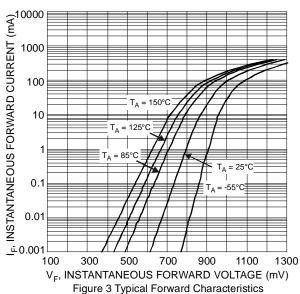
| Reverse Standoff Voltage | Volt | down age @ I _T | Test Current | Max. Reverse Leakage @ V _{RWM} (Note 6) | Max. Clampi V _C @ I _{PP} (| • | Max Total Capacitance C _T (Note 8) V _R = 1V | Typical Total Capacitance C _T (Note 8) V _R = 3.3V |
|--------------------------------|---------|---------------------------------|---------------------|--|---|---------------------|---|---|
| V _{RWM} (V) | Min (V) | Max (V) | I _T (mA) | I _R (μA) | V _C (V) | I _{PP} (A) | (pF) | (pF) |
| 5 | 6.1 | 8 | 1.0 | 0.25 | 12.5 | 2 | 9 | 5.4 |

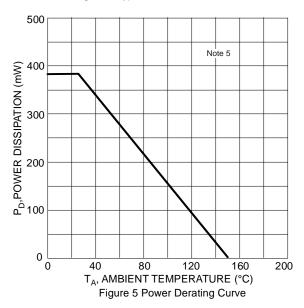
Notes:

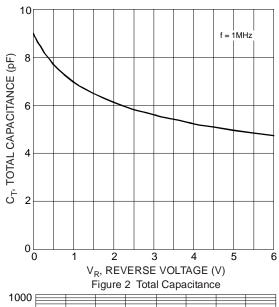
- 5. Device mounted on FR-4 PC board with suggested pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf. 6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an $8 \times 20 \mu s$ peak pulse current (I_{pp}) waveform.











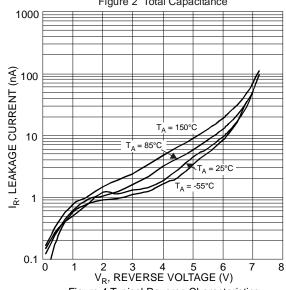


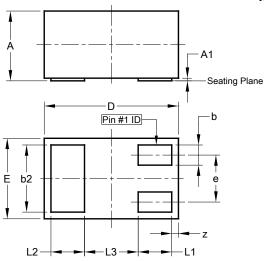
Figure 4 Typical Reverse Characteristics



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

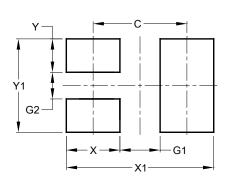
X1-DFN1006-3



| X1-DFN1006-3 | | | | |
|----------------------|------|-------|------|--|
| Dim | Min | Max | Тур | |
| Α | 0.47 | 0.53 | 0.50 | |
| A1 | 0.00 | 0.05 | 0.03 | |
| þ | 0.10 | 0.20 | 0.15 | |
| b2 | 0.45 | 0.55 | 0.50 | |
| D | 0.95 | 1.075 | 1.00 | |
| Е | 0.55 | 0.675 | 0.60 | |
| е | | _ | 0.35 | |
| L1 | 0.20 | 0.30 | 0.25 | |
| L2 | 0.20 | 0.30 | 0.25 | |
| L3 | _ | | 0.40 | |
| Z | 0.02 | 0.08 | 0.05 | |
| All Dimensions in mm | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



X1-DFN1006-3

| Dimensions | Value (in mm) |
|------------|---------------|
| С | 0.70 |
| G1 | 0.30 |
| G2 | 0.20 |
| Х | 0.40 |
| X1 | 1.10 |
| Y | 0.25 |
| Y1 | 0.70 |



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